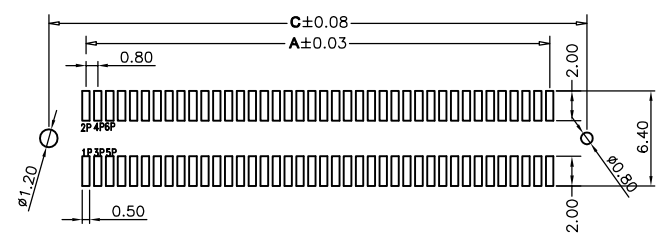
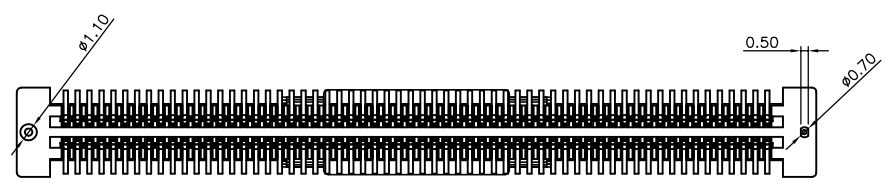
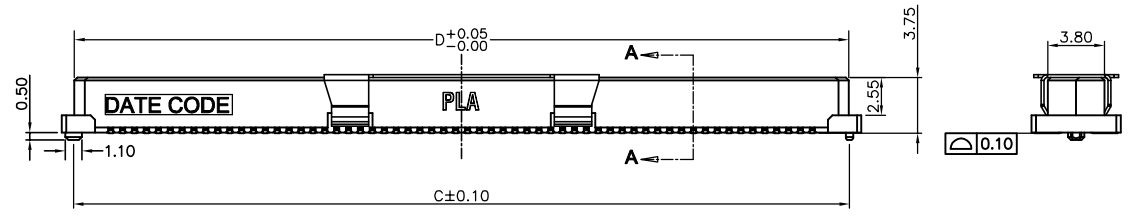
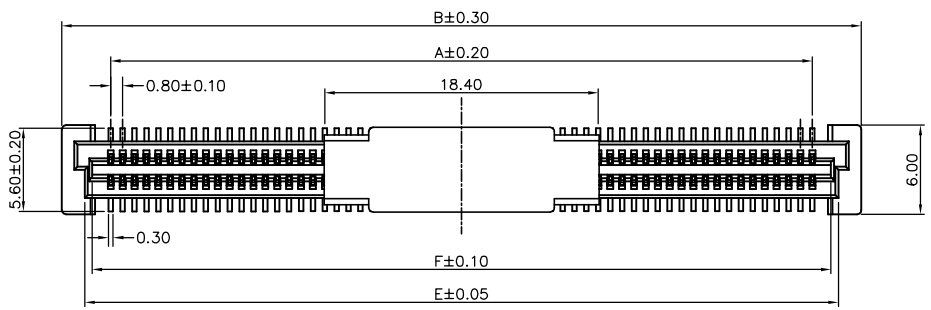


| REV | ECN. NO. | DESC. | APPD. |
|-----|----------|-------|---------------|
| A | WE210842 | 新版发行 | LWW 210820 |



RECOMMEND PCB LYOUT TOLERANCE ±0.05

- NOTES: (UNLESS OTHERWISE SPECIFIED)
- DIMENSION SHALL BE INTERPRETED PER ANSI Y14.5M-1994
 - INSERTION FORCE: 150g MAX. PER CONTACT.
 - WITHDRAW FORCE: 25g MIN. PER CONTACT.
 - DURABILITY: 30 CYCLES .
 - VOLTAGE RATING:50V AC
 - CURRENT RATING:0.5 AMPERE.
 - CONTACT RESISTANCE:50 m ohms MAX. FOR INITIAL.
 - DIELECTRIC WITHSTANDING VOLTAGE: 500V AC rms./MINUTE.
 - INSULATION RESISTANCE: 100 Megohms MIN..
 - HARMFUL MATERIAL SHOULD BE COMPLIANT TO STANDARDS.
 - PRODUCT NUMBER MATRIX:5001-BAP 0837- ** F R -00

The standby
 PACKING:R:REEL
 FEMALE
 PIN
 MATINGHEIGHT: 37-3.7H
 0.8BTB
 JM CONN BTB CONNECTOR SERIES

| CIRCUITS | DIM.A | DIM.B | DIM.C | DIM.D | DIM.E | DIM.F |
|----------|-------|-------|-------|-------|-------|-------|
| 40 | 15.20 | 21.80 | 20.20 | 20.10 | 18.70 | 17.70 |
| 60 | 23.20 | 29.80 | 28.20 | 28.10 | 26.70 | 25.70 |
| 80 | 31.20 | 37.80 | 36.20 | 36.10 | 34.70 | 33.70 |
| 100 | 39.20 | 45.80 | 44.20 | 44.10 | 42.70 | 41.70 |
| 120 | 47.20 | 53.80 | 52.20 | 52.10 | 50.70 | 49.70 |
| 140 | 55.20 | 61.80 | 60.20 | 60.10 | 58.70 | 57.70 |
| 160 | 63.20 | 69.80 | 68.20 | 68.10 | 66.70 | 65.70 |
| 180 | 71.20 | 77.80 | 76.20 | 76.10 | 74.70 | 73.70 |
| 200 | 79.20 | 85.80 | 84.20 | 84.10 | 82.70 | 81.70 |

| | | | | |
|-----------|------------------|-----------|-------------------------|------------------|
| X.±0.30 | .X± 0.25 | .XX± 0.20 | NAME<INTENDED USE>: | 东莞市文章济美电子有限公司 |
| X.'± 3' | .X'± 2' | .XX'± | 0.8MM BTB RECEP. | |
| UNITS: mm | DATE: 2021-08-20 | MAT'L | PART NO.<INTENDED USE>: | TITLE: |
| | | | 5001-BAP0837- **FR-00-B | CUSTOMER DRAWING |
| | | | APPD: | DWG NO.: |
| | | | CHKD: | 600-0000-0528 |
| | | | DR: | SCALE SHEET REV |
| | | | | N/A 1/4 A |

| | | | | |
|-----------------|---|-------------|---------------------|--------------|
| PLASTRON | 0.8 Pitch Board To Board CONNECTOR PRODUCT SPECIFICATION | Rev. | Document No. | SHEET |
| | | A | WI-RD-S004 | Page1 of 5 |

1. SCOPE

This product specification contains the test method, the general performance and property for 0.8 Pitch Board To Board connector

2. General items:

2.1 Application

This specification applies to the 0.8 Pitch Board To Board connector

2.2 Operating Temperature Range: -40~105 °C

2.3 Storage Temperature Range: -40~85 °C

3. PROPERTY

3.1 MATERIALS

| Item | Standard |
|---------|---|
| Housing | High Temperature Thermoplastic , UL 94V-0 |
| Contact | Copper Alloy, Gold plating |
| | |

3.2 RATINGS

| Item | Standard |
|---------------------------|------------------|
| Current Rating | 0.5 A AC/DC Max. |
| Voltage Rating | 50V AC/DC |
| Ambient Temperature Range | -40°C ~ +105°C |
| Storage Temperature Range | -40°C ~ +85°C |
| Ambient ` Range | 95 % R.H. Max. |

| | | | | |
|-----------------|---|-------------|---------------------|--------------|
| PLASTRON | 0.8 Pitch Board To Board CONNECTOR PRODUCT SPECIFICATION | Rev. | Document No. | SHEET |
| | | A | WI-RD-S004 | Page2 of 5 |

4. Test Methods and Requirements:

4.1 Electrical Performance

| Item | Test Item | Standard | Test Condition |
|-------|---------------------------------|--|---|
| 4.1.1 | Contact Resistance | It should be tested in accordance. (EIA-364-23) | 50 mΩ max. Initial |
| 4.1.2 | Insulation Resistance | Apply a voltage of AC 500V for 2 minutes between adjacent terminals and measure. (EIA-364-21C) | 100 MΩ min. Initial 50 MΩ min. Final |
| 4.1.3 | Dielectric Withstanding Voltage | Apply a voltage of AC 500V for 60±5s to between adjacent terminals. | There must be no breakdown. |

4.2 Mechanical Performance:

| | | | |
|-------|-------------------------|---|---------------------------------------|
| 4.2.1 | Contact Retention force | Pull connectors at maximum rate of 25mm/minute. | 200 grams min./per contact |
| 4.2.2 | Insertion force | Plug insert into socket shell be an alignment at a constant speed of 25mm/minute. | 150gf Max per contact |
| 4.2.3 | Withdrawal force | Plug pull out socket shell be an alignment at a constant speed of 25mm/minute | 25gf Min per contact |
| 4.2.4 | Durability | EIA-364-09C Connector shall be subjected to 30cycles of Insertion and withdrawal | 50mΩ max. initial 70 mΩ max. Final |

| | | | | |
|-----------------|---|-------------|---------------------|--------------|
| PLASTRON | 0.8 Pitch Board To Board CONNECTOR PRODUCT SPECIFICATION | Rev. | Document No. | SHEET |
| | | A | WI-RD-S004 | Page3 of 5 |

| | | | |
|-------|-----------|--|--|
| 4.2.5 | Vibration | 10-55-10 Hz/min. Amplitude: 1.52mm Period: 2 hours for each direction X,Y,Z axis. (EIA-364-28E) | No electrical discontinuity greater than 1 microseconds shall occur. |
| 4.2.6 | Drop | 76cm Height one carton 6-sydes random dropping. | [Appearance] No abnormality [Function] OK |

4.3 Environmental Performance:

| | | | |
|-------|---------------|---|--|
| 4.3.1 | Thermal shock | EIA-364-32C, Condition I. One cycle consists of: -55°C for 30 minutes/+85°C for 30 minutes. Times of cycle: 5 cycles. | See Note 50mΩ max. initial 70 mΩ max Final |
| 4.3.2 | Humidity | EIA-364-31B, Method II, Condition A Temperature: 40 ±2°C Humidity: 90 ~ 95 % (RH) Period: 96 hours | See Note 50mΩ max. Initial 70 mΩ max Final |
| 4.3.3 | Salt Spray | EIA-364-26B, Condition A. Temperature: 35±2°C , Density 5% in weight. Period24 hours | 50mΩ max. initial 70 mΩ max Final |

4.4 Others

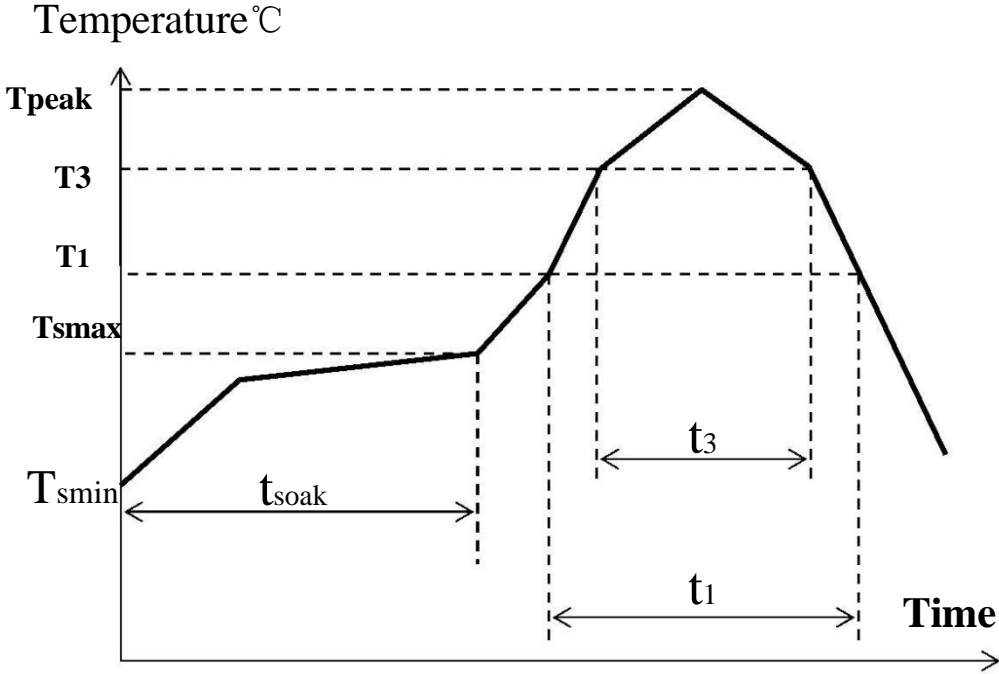
| | | | |
|-------|---------------------|--|-----------------------------|
| 4.4.1 | Solder ability | EIA-364-52 Temperature: 245+/-5°C,3~5sec | See Note 95%min |
| 4.4.2 | Temperature Life | EIA-364-17A, method A Condition 4. Temperature : 105 ± 2 °C Period250 hours | See Note 70 mΩ max Final |

NOTE: Shall meet visual requirements , show no physical damages.

| | | | | |
|-----------------|---|-------------|---------------------|--------------|
| PLASTRON | 0.8 Pitch Board To Board CONNECTOR PRODUCT SPECIFICATION | Rev. | Document No. | SHEET |
| | | A | WI-RD-S004 | Page4 of 5 |

5. Reflow Profile for soldering heat resistance testing

| Reflow Profile for soldering heat resistance testing | | |
|--|--------|---------------------------------------|
| Parameter | Mark | Major parts |
| Speed of temperature-raising | | Not raise over 3°C for each second |
| Temperature Min (Ts min) | Ts min | 150°C |
| Temperature Max (Ts max) | Ts max | 200°C |
| Time (ts min to ts max) | Ts | 2~3minutes |
| Time of temperature over 217°C | t 1 | 60~150seconds |
| At the reflow area | t 3 | 20~40 seconds (t 3) |
| | T3 | (T3) |
| At the highest temperature | T peak | 260(+0/-5°C) |
| Speed of temperature-decreasing | | Not decrease over 6°C for each second |
| Time from 25°C to highest temperature | | Not over 8 minutes |



SMT TYPE Re-flow profile for soldering heat(Lead free)

